

Part Number: XZFDGK14C2

SURFACE MOUNT DISPLAY

Features

- 0.56 inch digit height
- Robust package
- Low power consumption
- Standard configuration: Gray face w/ white segments
- Standard Package: 200pcs/ Reel • MSL (Moisture Sensitivity Level): 2a
- RoHS Compliant

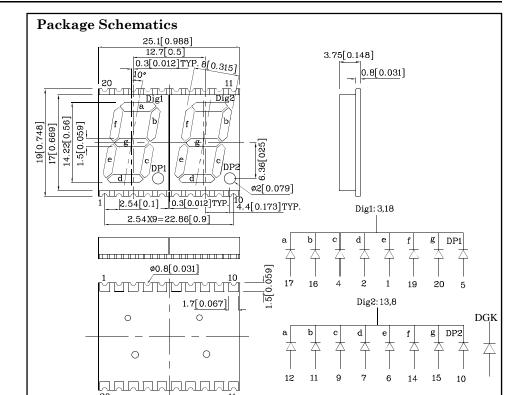






ATTENTION

OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES



Notes:

- 1. All dimensions are in millimeters (inches), Tolerance is ±0.25(0.01")unless otherwise noted.
- 2. Specifications are subject to change without notice.
- 3. The gap between the reflector and PCB shall not exceed 0.25mm.

Absolute Maximum Ratings (T _A =25°C)		DGK (InGaN)	Unit	
Reverse Voltage	V_{R}	5	V	
Forward Current	I_{F}	25	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i_{FS}	150	mA	
Power Dissipation P _D		102.5	mW	
Operating Temperature	$T_{\rm A}$	-40 ~ +85	°C	
Storage Temperature	Tstg	-40 ~ +85		
Electrostatic Discharge Threshold (HBM)		450	V	

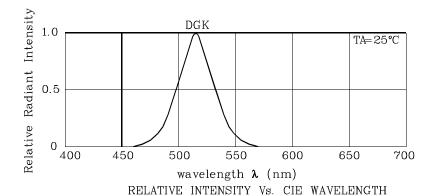
Operating Characteristics (T _A =25°C)		DGK (InGaN)	Unit
Forward Voltage (Typ.) (I _F =10mA)	V_{F}	3	V
Forward Voltage (Max.) (I _F =10mA)	V_{F}	4.1	V
Reverse Current (Max.) (V _R =5V)	I_R	50	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =10mA)	λΡ	515*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =10mA)	λD	525*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA)	$\triangle \lambda$	35	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	45	pF

Part Number	Emitting Color	Emitting Material	Luminous Intensity CIE127-2007* $(I_F=10 \mathrm{mA})$ ucd	Wavelength CIE127-2007* nm λP	Description
			min. typ.		
XZFDGK14C2	Green	InGaN	52000 159990 21000* 50990*	515*	Common Cathode, Rt. Hand Decimal

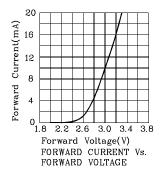
^{*}Luminous intensity value and wavelength are in accordance with CIE127-2007 standards. Jan 13,2014

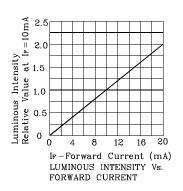


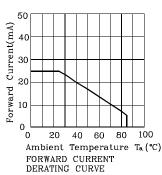


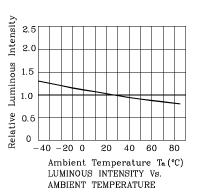


❖ DGK



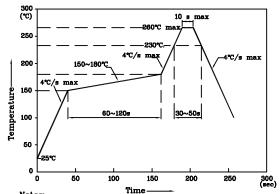






LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)

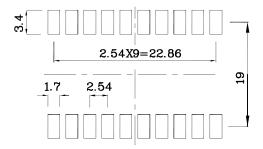


- Notes:
 1. Maximum soldering temperature should not exceed 260°C
- 2. Recommended reflow temperature: 145°C-260°C
- 3. Do not put stress to the epoxy resin during high temperatures conditions

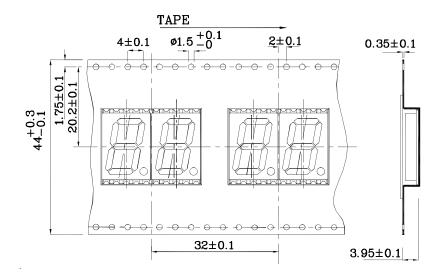




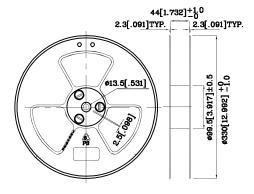
❖ Recommended Soldering Pattern (Units: mm; Tolerance: ±0.15)



❖ Tape Specification (Units:mm)



* Reel Dimension



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

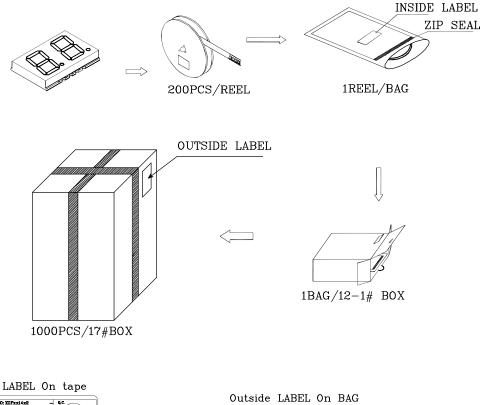
- 1. Wavelength: +/-1nm
- 2. Luminous intensity / luminous flux: +/-15%
- 3. Forward Voltage: +/-0.1V

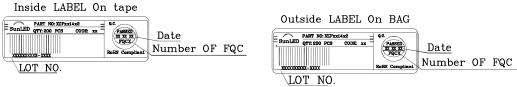
Note: Accuracy may depend on the sorting parameters.

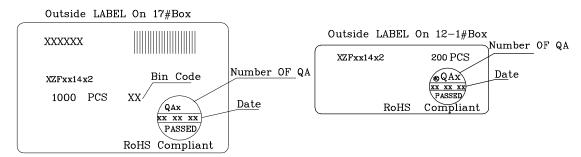




PACKING & LABEL SPECIFICATIONS







TERMS OF USE

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- 2. Contents within this document are subject to improvement and enhancement changes without notice.
- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet. User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
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